

## BGA Inspection System

### 3D Rotary Ring

A 3-D rotary ring allows the inspector to see under the component and examine the contacts at exactly the most appropriate angle. Whether slightly above or below horizontal, or slightly left or right of straight ahead, the Rotary Ring provides further degree of control while inspecting in tight spaces.

### Shock Absorber

The BGA lens has a spring built-in as shock absorber. Whenever lens touches the board, it gives an extra protection for lens as well as the board. The replaceable BGA prism chip gives additional protection for both the board and lens itself.

### Prism Chip

With a width of 0.9mm, the prism chip can deliver a clear image even when components are mounted very near each other. External lighting is also collected and sent through the chip, directing concentrated light under the BGA sample.

### Light Pen

Allow the user to direct concentrated light to the exact point of desired inspection. Such concentrated lighting helps to create the brightest, highest resolution images of surface details to be seen on the individual solder balls under the BGA component.

### Bubble Level Gauge

Provided to help the user to confirm and adjust to a true horizontal position for the inspection sample.

### Light Station

There are 5 ports available. 3 ports are allocated for 2 flexible arms and 1 for prism chip as a illumination from front. 2 residual port can be added by more flexible arms for convenience.

### Zooming

The Hirox BGA inspection system has a magnification range of 50x to 200x. The front row of balls is seen at higher magnification and the magnification decreases as balls are viewed farther back inside. Hirox provides full screen images of the critical BGA contact areas.

### Flexible Arms

Allows the user to position the various lighting tools exactly in the position and from the angle that provides the best light at all times. 2 flexible arm are included with the lens, however 2 additional arms can be added to light station

